| 19 | L Number | Hits | Search Text | DB | Time stamp |
|--|------------|----------|--|---------|--------------------|
| dioxide or silicon adj oxide) and (ultra adj violet or uv) and cvd SP-GPUB, EPO, JPO; DERMENT; ISM TOB plasma Colored SP-GPUB, EPO, JPO; DERMENT; ISM TOB USPAT; US-FGPUB, EPO, JPO; DERMENT; | - | 46 | low adj temperature near7 (silicon adj | | |
| adj violet or uv) and cvd | | | dioxide or silicon adj oxide) and (ultra | | 2002,03,21 20.01 |
| Sara | | | | | |
| Safe Silicon adj dioxide or silicon adj Silicon | | | | | |
| - | 1 | | | | [|
| nitride and atmospheric adj pressure and plasma US-FGFUB; PRO; JPO; DERWENT; IBM TDB USPAT; US-FGFUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAGEUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAGEUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAGEUB; EPO; JPO; DERWENT; | _ | 3478 | (silicon adi dioxide or silicon adi | | 2002/09/20 16:11 |
| Plasma | | | nitride) and atmospheric adj pressure and | | 2002, 03, 20 10.11 |
| DERMENT; IBM TOB USPAT; | | | | | |
| TIM TOB SPAT; US-REFUB; EPG; JPG; DERWENT; IN TOB SPAT; US-R | | | • | | |
| - 7835 noble adj gas | | | | | |
| Separation | _ | 7835 | noble adi gas | | 2002/09/20 16:11 |
| - 96 | | | | 1 | 2002,05,20 10.11 |
| Performance | | | | | |
| 96 | | | | | |
| - 96 ((silicon adj dioxide or silicon adj intride) and atmospheric adj pressure and plasma) and (noble adj gas) USPĀT, US-PGFUB, PO, JPO, DERWENT; IBM TDB USPĀT; US-PGFUB, PO, JPO, DERWENT; | | 1 | | · · | |
| | l - | 96 | ((silicon adi dioxide or silicon adi | | 2002/09/20 16:55 |
| Plasma) and (noble adj gas) EPO; JPO; DERMENT; IBM TDB USPAT; US-PCPUB; EPO; JPO; DERMENT; IBM TDB USPAT; | | , , | | | 2002/03/20 10:55 |
| 1494 apcvd or "atmospheric pressure chemical vapor deposition" DERWENT; INM TDB USPAT; US-PCPUB; EPO; JPO; DERWENT; INM TDB USPAT; US-PCPUB; EPO; JP | | 1 | plasma) and (noble add gas) | | |
| 1494 apcvd or "atmospheric pressure chemical vapor deposition" USPAT; USP | | | prasma, and (nobie ad) gas, | | |
| 1494 apcvd or "atmospheric pressure chemical vapor deposition" USPĀT; US-PGUB; EPO; JPO; DERWENT; IBM TDB | | | | | |
| Vapor deposition" | _ | 1494 | ancyd or "atmospheric pressure chemical | | 2002/00/21 11:47 |
| Company Comp | | 1,1,1 | | 1 | 2002/09/21 11:4/ |
| ORWENT; DERWENT; DERWENT; SPAT; US-PGPUB; PRO USPAT; | | | Tapos deposition | | |
| TIM TDB 18PAT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPAT; US- | 63 18 | | | | |
| Coble adj gas) and (apcvd or "atmospheric pressure chemical vapor deposition") | | | | | |
| Pressure chemical vapor deposition") | _ | 31 | (noble add gas) and (angud or "atmospheric | | 2002/00/20 16 56 |
| 249 | |) , | | 1 | 2002/09/20 16:56 |
| - 127583 argon | | | pressure chemical vapor deposition) | 1 | • |
| TEM TDB USPAT; US-FGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US- | | | | 1 | |
| - 127583 argon | | | | | |
| 127583 argon | _ | 2/19 | "90" add kna or "110" add kna | | 2002/00/20 17.46 |
| Topic Property P | | 243 | 30 adj kpa of 110 adj kpa | 1 | 2002/09/20 17:46 |
| DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB U | 0.1 | | | 1 | |
| 127583 argon | \ | | | £ | |
| 127583 argon | | | | | |
| S-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; U | | 127502 | | | 0000/00/00 17 |
| SPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; USPĀT; US-PGPUB; USP | | 12/303 | argon | , | 2002/09/20 17:44 |
| Comparison of the property o | | 1 | | 1 | |
| 33 ("90" adj kpa or "110" adj kpa) and argon IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_T | | | | | |
| - 274720 wafer 274 | 0 11 | | | | |
| US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; USPĀT US | | 33 | ("90" add leng on "110" add leng) and assess | | 0000/00/00 17 44 |
| 274720 wafer EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; | | 33 | (30 ad) kpa of 110 ad) kpa) and argon | | 2002/09/20 17:44 |
| DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT | 1 | | | 1 | |
| TBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPU | | | | | |
| - 274720 wafer 274720 wafer | | | | | |
| US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; | _ | 274720 | for | | 0000/00/00 15 15 |
| The content of the | - 0.41 | 2/4/20 | water | | 2002/09/20 17:46 |
| - 11 ("90" adj kpa or "110" adj kpa) and wafer DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; US-PGP | | | | | |
| TBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; | | | | | |
| - 11 ("90" adj kpa or "110" adj kpa) and wafer USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; | | | | | |
| 1249 apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa) 2002/09/21 12:54 | _ | 11 | ("90" add kpa or "110" add kpa) andf | | 2002/00/00 17 16 |
| - 1249 apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa) - 621 wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa) - 62266 noble EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; | 1 | 11 | () o adj kpa of fito adj kpa) and water | · · | 2002/09/20 1/:46 |
| DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; | | | | | |
| apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa) - 621 wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa) - 62266 noble IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; USPAT; US-PGPUB; | | | | , | |
| apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa) Wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa) Wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa)) Wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa)) Wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "150" US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; US-PGPUB; US-PGPUB; | | | | | |
| vapor deposition" and ("90" adj kpa or "110" adj kpa) 621 wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa)) 62266 noble Vapor deposition" and ("90" adj US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; US-PGPUB; | | 1240 | anoud or "atmosphoric proceums chemical | | 2002/00/01 10 5: |
| "110" adj kpa) EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; US-PGPUB; US-PGPUB; | | 1243 | | 1 | 2002/09/21 12:54 |
| - 621 wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa)) - 62266 noble DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB; | | | | | |
| - 621 wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa)) - 62266 noble IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; US-PGPUB; US-PGPUB; | | | ττο αυμπραί | | |
| - 621 wafer and (apcvd or "atmospheric pressure chemical vapor deposition" and ("90" adj kpa or "110" adj kpa)) - 62266 noble USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; | | | | | |
| chemical vapor deposition" and ("90" adj kpa or "110" adj kpa)) Chemical vapor deposition" and ("90" adj kpa) US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; | _ | 621 | wafer and langued on Wetmoonhand | | 2002/02/22 == |
| kpa or "110" adj kpa)) EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; | - | 021 | chomical mapor denseitien" and ("00" and | | 2002/09/20 17:50 |
| DERWENT; IBM TDB USPAT; US-PGPUB; | | | kps or "110" add heal) | | |
| IBM_TDB USPAT; US-PGPUB; | İ | | kpa or "IIo" adj Kpa)) | , | |
| - 62266 noble USPAT; 2002/09/21 12:59 US-PGPUB; | | | | | |
| US-PGPUB; | | 62266 | mahla | | 0000/00/ |
| | - | 62266 | nobte | | 2002/09/21 12:55 |
| EPO; JPO; | | | | | |
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| | | chemical vapor deposition" and ("90" adj | US-PGPUB; | |
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| - | 25043 | | USPAT; | 2002/09/21 11:47 |
| | | atm or "1" adj atmosphere or "760mm" | US-PGPUB; | |
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| | | | DERWENT; | |
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| - 1 | 1270 | apcvd or "atmospheric pressure chemical | USPAT; | 2002/09/21 11:47 |
| | | vapor deposition" and ("100" adj kpa or | 1 | 2002/09/21 11:4/ |
| 1 | | "760" add town on "1" add town of | US-PGPUB; | |
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| | | atmosphere or "760mm") | DERWENT; | |
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| 1 | | "1" adj atmosphere or "760mm")) | DERWENT; | |
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|] - | 69 | , | USPAT; | 2002/09/21 12:12 |
| 1 | | adj process) and semiconductor | US-PGPUB; | |
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| | | processing) | US-PGPUB; | |
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| _ | 47 | noble and (apcvd or "atmospheric pressure | USPAT; | 2002/09/21 12:55 |
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| | | enemical vapor deposition and uv and ri) | US-PGPUB; | ļ |
| | 11 | • | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM TDB | |
| - | 14 | low adj temperature near7 (silicon adj | USPĀT; | 2002/09/21 13:52 |
| | | dioxide or silicon adj oxide) and (ultra | US-PGPUB; | |
| | | adj violet or uv) and cvd and alloy | EPO; JPO; | |
| | | and cva and arroy | · | |
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